MOSFET - N-Channel, SUPERFET® II, FRFET®

650 V, 54 A, 77 m Ω

FCH077N65F-F085

Description

SuperFET II MOSFET is ON Semiconductor's brand-new high voltage super-junction (SJ) MOSFET family that is utilizing charge balance technology for outstanding low on-resistance and lower gate charge performance. This technology is tailored to minimize conduction loss, provide superior switching performance, dv/dt rate and higher avalanche energy. Consequently SuperFET II is very well suited for the Soft switching and Hard Switching topologies like High Voltage Full Bridge and Half Bridge DC-DC, Interleaved Boost PFC, Boost PFC for HEV-EV automotive.

SuperFET II FRFET MOSFET's optimized body diode reverse recovery performance can remove additional component and improve system reliability.

Features

- Typ. $R_{DS(on)} = 68 \text{ m}\Omega$ at $V_{GS} = 10 \text{ V}$, $I_D = 27 \text{ A}$
- Typ. $Q_{g(tot)} = 126 \text{ nC}$ at $V_{GS} = 10 \text{ V}$, $I_D = 27 \text{ A}$
- UIS Capability
- AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free and are RoHS Compliant

Applications

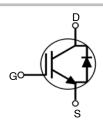
- Automotive On Board Charger
- Automotive DC/DC Converter for HEV



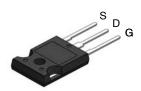
ON Semiconductor®

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V _{DS}	R _{DS(ON)} MAX	I _D MAX	
650 V	77 mΩ @ 10 V	54 A	

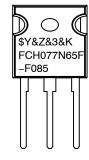


N-CHANNEL MOSFET



TO-247-3LD CASE 340CK

MARKING DIAGRAM



\$Y

&Z

= ON Semiconductor Logo

Assembly Plant CodeNumeric Date Code

&3 = Numeric Da &K = Lot Code

FCH077N65F-F085 = Specific Device Code

ORDERING INFORMATION

See detailed ordering and shipping information on page 2 of this data sheet.

ABSOLUTE MAXIMUM RATINGS ($T_C = 25^{\circ}C$ unless otherwise noted)

Symbol	Parameter	Value	Unit
V _{DSS}	Drain to Source Voltage	650	V
V_{GSS}	Gate to Source Voltage	±20	V
I _D	Drain Current – Continuous (V _{GS} = 10) (Note 1)	54	А
	Pulsed Drain Current	See Fig. 4	Α
E _{AS}	Single Pulsed Avalanche Rating (Note 2)	1128	mJ
dv/dt	MOSFET dv/dt	100	V/ns
	Peak Diode Recovery dv/dt (Note 3)	50]
P_{D}	Power Dissipation	481	W
	Derate Above 25°C	3.85	W/°C
T _J , T _{STG}	Operating and Storage Temperature Range	-55 to + 150	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

- 1. Current is limited by bondwire configuration.
- 2. Starting $T_J = 25$ °C, L = 18.65 mH, $I_{AS} = 11$ A, $V_{DD} = 100$ V during inductor charging and $V_{DD} = 0$ V during time in avalanche. 3. $I_{SD} \le 27$ A, $di/dt \le 200$ A/µs, $V_{DD} \le 380$ V, starting $T_J = 25$ °C.

PACKAGE MARKING AND ORDERING INFORMATION

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FCH077N65F	FCH077N65F-F085	TO-247-3	-	-	30 Units

THERMAL CHARACTERISTICS

Symbol	Parameter	Value	Unit
$R_{ heta JC}$	R _{θJC} Thermal Resistance, Junction to Case, Max.		°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient, Max. (Note 4)	40	

^{4.} R_{0,JA} is the sum of the junction-to-case and case-to-ambient thermal resistance, where the case thermal reference is defined as the solder mounting surface of the drain pins. $R_{\theta JC}$ is guaranteed by design, while $R_{\theta JA}$ is determined by the board design. The maximum rating presented here is based on mounting on a 1 in² pad of 2oz copper.

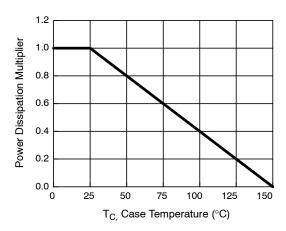
ELECTRICAL CHARACTERISTICS (T_C = 25°C unless otherwise noted)

Symbol	Parameter	Test Condition		Min.	Тур.	Max.	Unit
OFF CHARA	ACTERISTICS					•	
BV _{DSS}	Drain to Source Breakdown Voltage	I _D = 250 μA, V _{GS} = 0 V		650	_	_	V
I _{DSS}	Drain to Source Leakage Current	$V_{DS} = 650 \text{ V},$	T _J = 25 °C	-	-	10	μΑ
		V _{GS} = 0 V	T _J = 150 °C (Note 5)	-	-	1	mA
I _{GSS}	Gate to Source Leakage Current	V _{GS} = ±20 V		=	-	±100	nA
ON CHARA	CTERISTICS						
V _{GS(th)}	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_D =$	250 μΑ	3	-	5	V
R _{DS(on)}	Drain to Source On Resistance	I _D = 27 A	T _J = 25 °C	-	68	77	mΩ
		V _{GS} = 10 V	T _J = 150 °C (Note 5)	-	154	184	mΩ
YNAMIC C	HARACTERISTICS						
C _{iss}	Input Capacitance	V _{DS} = 25 V, V _{GS}	_S = 0 V,	-	5385	7162	pF
C _{oss}	Output Capacitance	f = 1 MHz		=	5629	7486	pF
C _{rss}	Reverse Transfer Capacitance			-	194	_	pF
C _{oss(eff.)}	Effective Output Capacitance	V _{DS} = 0 V to 520 V, V _{GS} = 0 V		-	693	-	pF
Rg	Gate Resistance	f = 1 MHz		-	0.5	-	Ω
Q _{g(tot)}	Total Gate Charge	$V_{DD} = 380 \text{ V}, I_{D}$	= 27 A _,	-	126	164	nC
Q _{g(th)}	Threshold Gate Charge	V _{GS} = 10 V	V _{GS} = 10 V		9	12	nC
Q _{gs}	Gate to Source Gate Charge			-	28	_	nC
Q_{gd}	Gate to Drain "Miller"Charge			=	53	-	nC
WITCHING	CHARACTERISTICS						
t _{on}	Turn-On Time	$V_{DD} = 380 \text{ V, } I_{D}$		-	64	148	ns
t _{d(on)}	Turn-On Delay Time	$V_{GS} = 10 \text{ V, R}_{G}$	= 4.7 \Q	=	37	-	ns
t _r	Rise Time			-	27	_	ns
t _{d(off)}	Turn-Off Delay Time			-	105	_	ns
t _f	Fall Time			-	5.3	_	ns
t _{off}	Turn-Off Time			-	108.3	237	ns
RAIN-SOU	RCE DIODE CHARACTERISTICS						
V _{SD}	Source to Drain Diode Voltage	V _{GS} = 0 V, I _{SD} =	= 27 A	-	-	1.2	V
t _{rr}	Reverse Recovery Time	V _{DD} = 520 V, I _F	= 27 A,	-	190	-	ns
Q _{rr}	Reverse Recovery Charge	$di_{SD}/dt = 100 \text{ A}/\mu\text{s}$		_	1.5	_	μC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

5. The maximum value is specified by design at $T_J = 150^{\circ}$ C. Product is not tested to this condition in production.

TYPICAL CHARACTERISTICS



60 V_{GS} = 10V

V_{GS} = 10V

V_{GS} = 10V

V_{GS} = 10V

T_C, Case Temperature (°C)

Figure 1. Normalized Power Dissipation vs.

Case Temperature

Figure 2. Maximum Continuous Drain Current vs.

Case Temperature

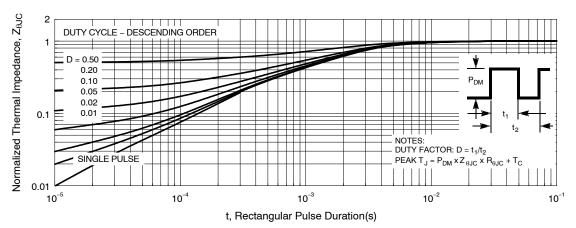


Figure 3. Normalized Maximum Transient Thermal Impedance

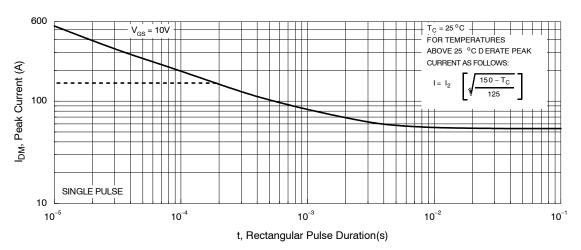


Figure 4. Peak Current Capability

TYPICAL CHARACTERISTICS

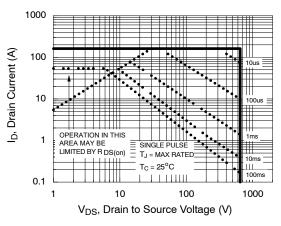


Figure 5. Forward Bias Safe Operating Area

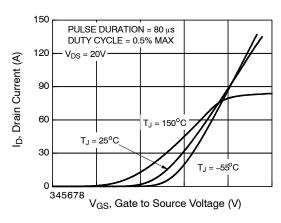


Figure 6. Transfer Characteristics

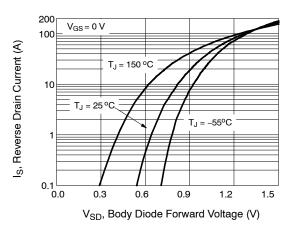


Figure 7. Forward Diode Characteristics

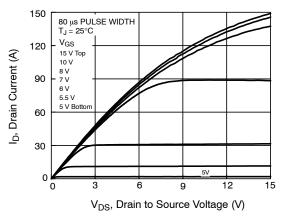


Figure 8. Saturation Characteristics

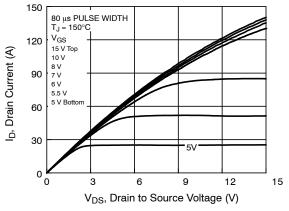


Figure 9. Saturation Characteristics

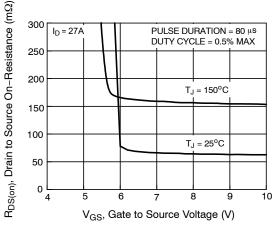


Figure 10. R_{DSON} vs. Gate Voltage

TYPICAL CHARACTERISTICS

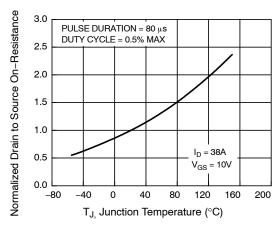


Figure 11. Normalized R_{DSON} vs. Junction

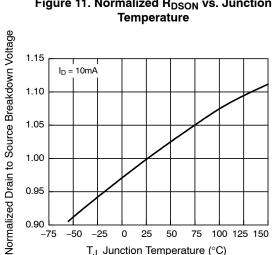


Figure 13. Normalized Drain to Source Breakdown Voltage vs. Junction Temperature

T_{J.} Junction Temperature (°C)

0 25 50

-50

75

100 125 150

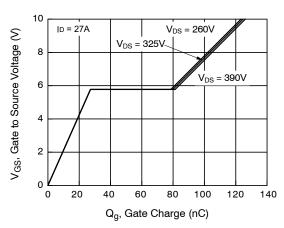


Figure 15. Gate Charge vs. Gate to Source Voltage

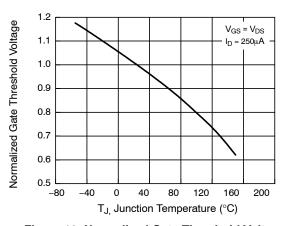


Figure 12. Normalized Gate Threshold Voltage vs. **Temperature**

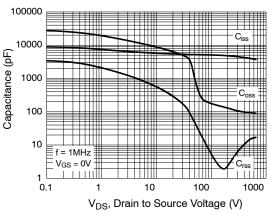


Figure 14. Capacitance vs. Drain to Source Voltage

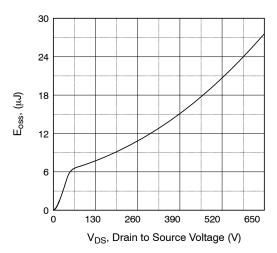


Figure 16. Eoss vs. Drain to Source Voltage

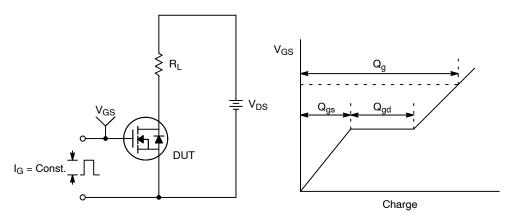


Figure 17. Gate Charge Test Circuit & Waveform

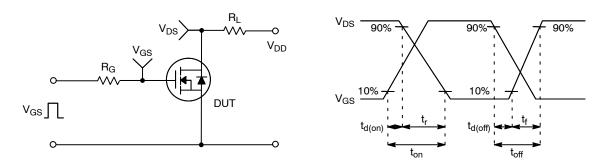


Figure 18. Resistive Switching Test Circuit & Waveforms

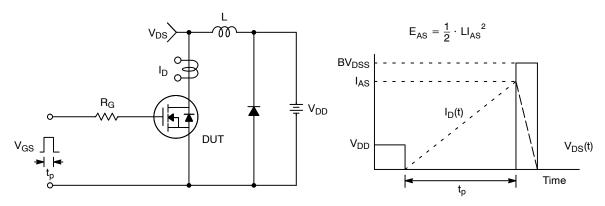


Figure 19. Unclamped Inductive Switching Test Circuit & Waveforms

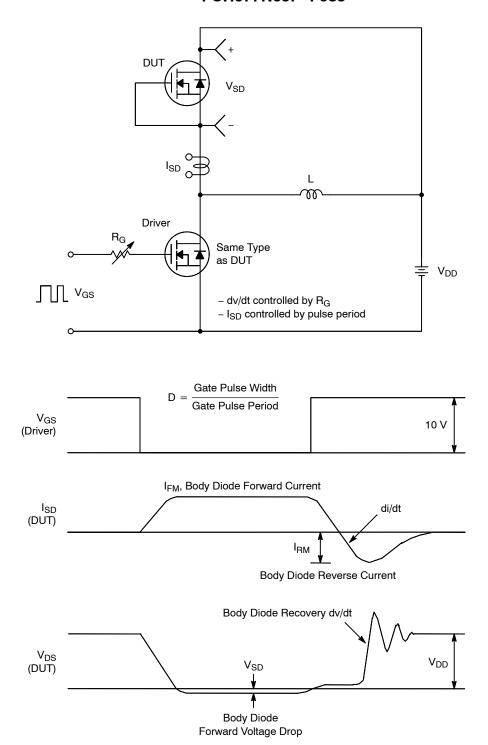


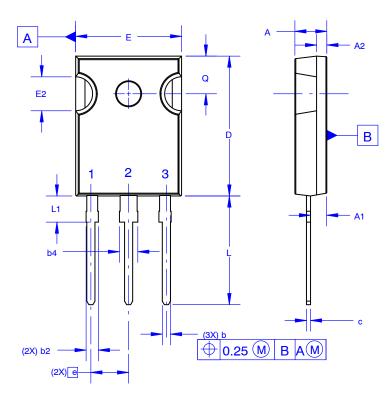
Figure 20. Peak Diode Recovery dv/dt Test Circuit & Waveforms

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TO-247-3LD SHORT LEAD

CASE 340CK ISSUE A



NOTES: UNLESS OTHERWISE SPECIFIED.

- A. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
- B. ALL DIMENSIONS ARE IN MILLIMETERS.
- C. DRAWING CONFORMS TO ASME Y14.5 2009.
- D. DIMENSION A1 TO BE MEASURED IN THE REGION DEFINED BY L1.
- E. LEAD FINISH IS UNCONTROLLED IN THE REGION DEFINED BY L1.

GENERIC MARKING DIAGRAM*



XXXX = Specific Device Code

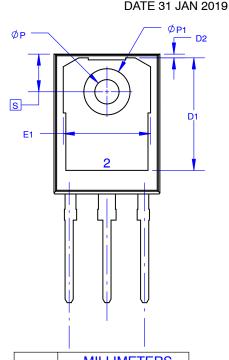
A = Assembly Location

Y = Year

WW = Work Week

ZZ = Assembly Lot Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.



DIM	MILLIMETERS			
DIIVI	MIN	NOM	MAX	
Α	4.58	4.70	4.82	
A1	2.20	2.40	2.60	
A2	1.40	1.50	1.60	
b	1.17	1.26	1.35	
b2	1.53	1.65	1.77	
b4	2.42	2.54	2.66	
С	0.51	0.61	0.71	
D	20.32	20.57	20.82	
D1	13.08	~	~	
D2	0.51	0.93	1.35	
E	15.37	15.62	15.87	
E1	12.81	~	~	
E2	4.96	5.08	5.20	
е	~	5.56	~	
L	15.75	16.00	16.25	
L1	3.69	3.81	3.93	
ØΡ	3.51	3.58	3.65	
ØP1	6.60	6.80	7.00	
Q	5.34	5.46	5.58	
S	5.34	5.46	5.58	

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DESCRIPTION:	TO-247-3LD SHORT LEAD		PAGE 1 OF 1	

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